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Applicant(s) Hedler et al.
COMMUNICATION WAFER LEVEL PACKAGING

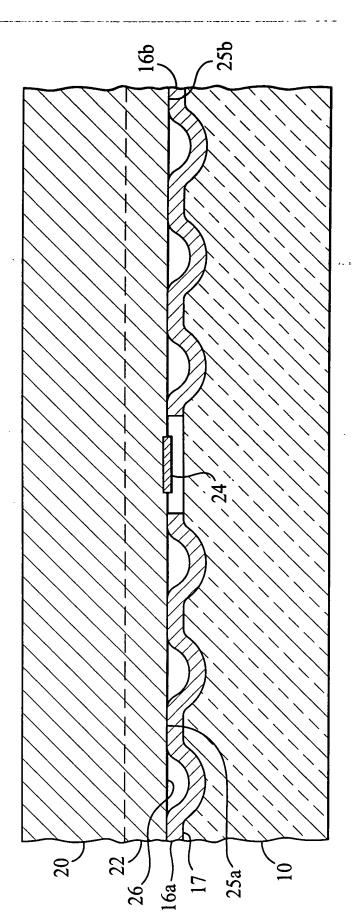
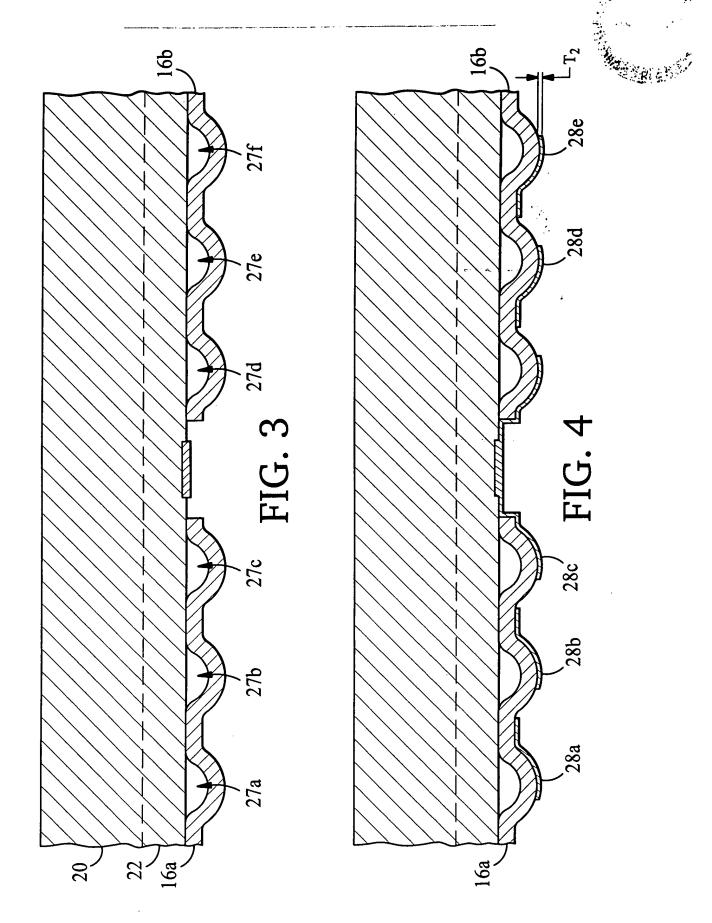


FIG. 2



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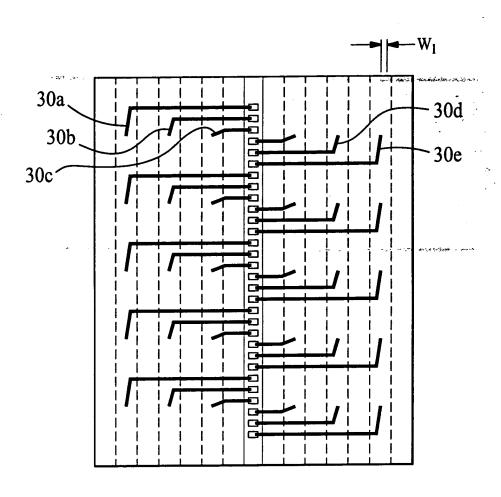
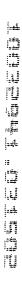
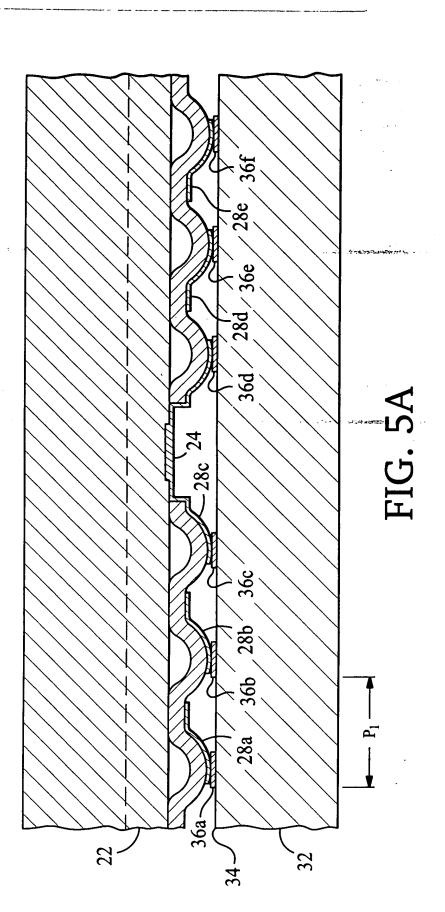
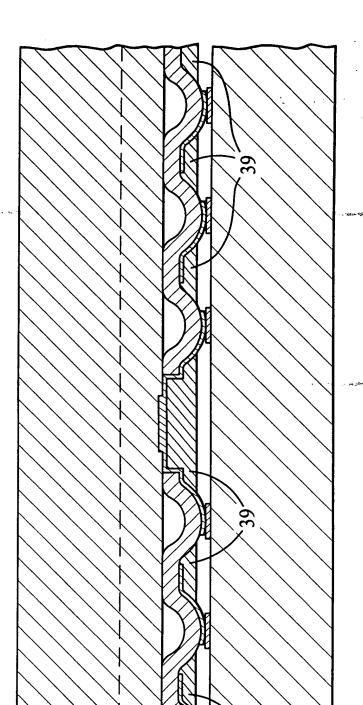


FIG. 4A





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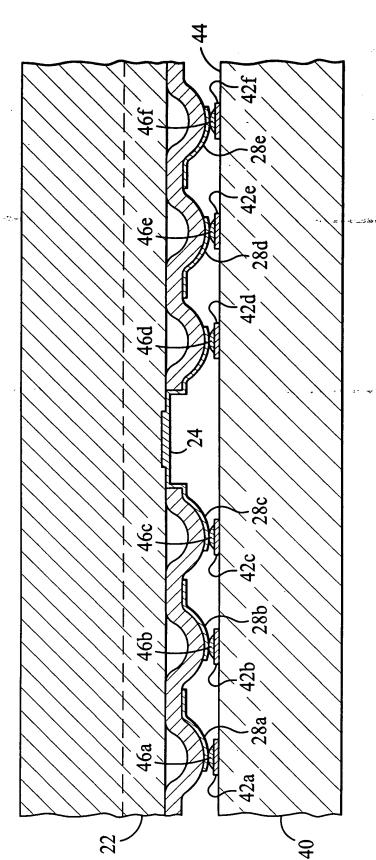
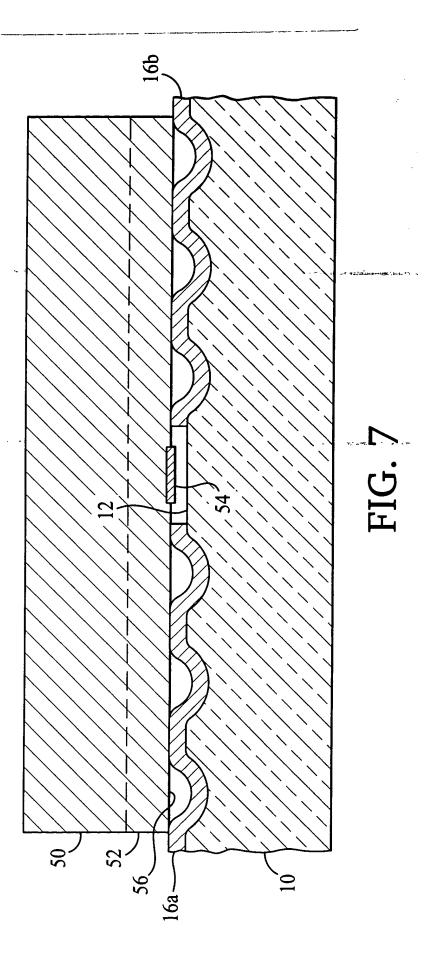


FIG. 6



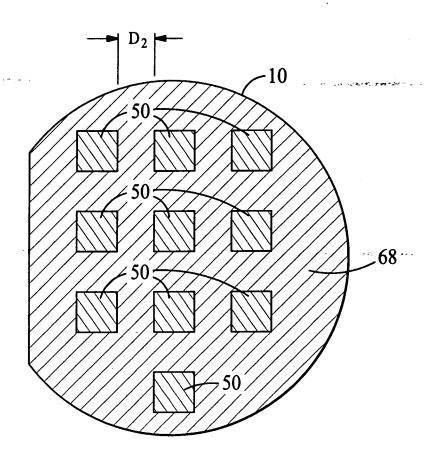


FIG. 7A

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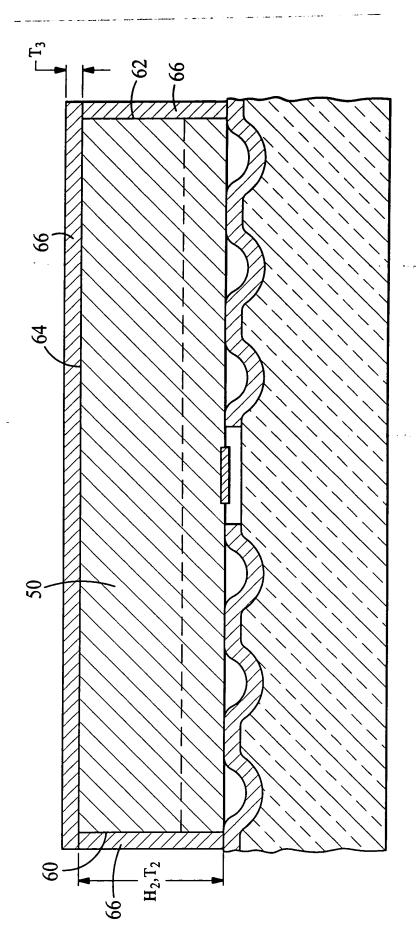


FIG. 8

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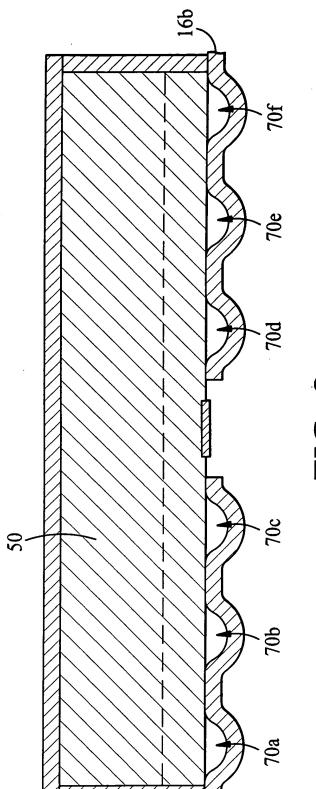


FIG. 9

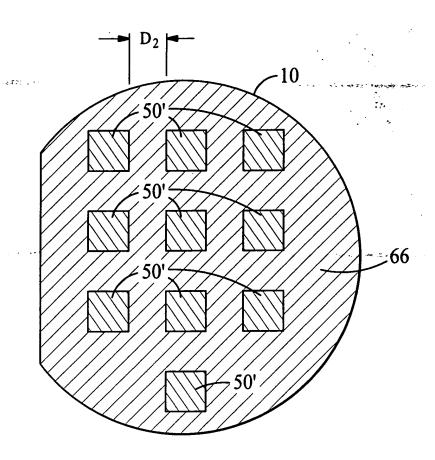
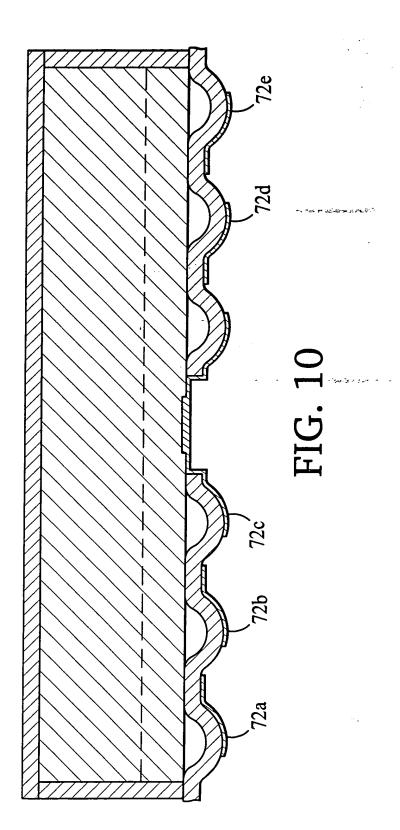


FIG. 9A





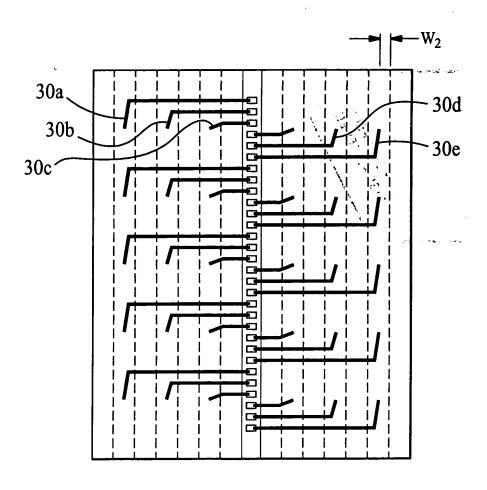
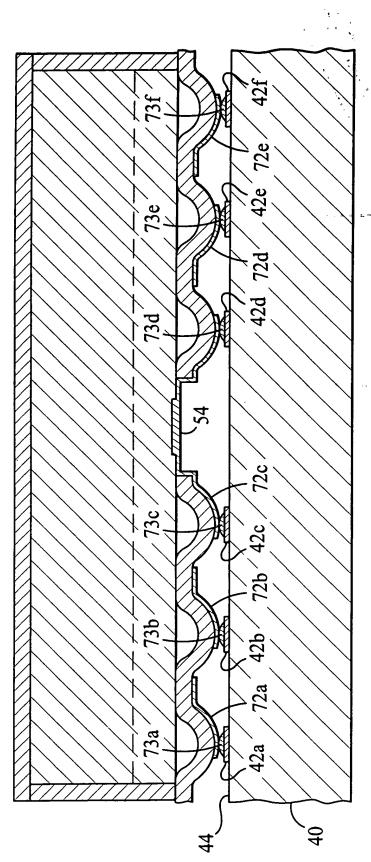


FIG. 10A

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